

## **FLIPCHIP INTERNATIONAL ANNOUNCES SUCCESSFUL COMPLETION OF ACQUISITION OF ASSETS OF IC SERVICES**

PHOENIX, Arizona, January 25, 2005—FlipChip International, LLC today announced the successful completion of its acquisition of substantially all of the assets of IC Services, Inc. IC Services assets include substantial dicing, automated inspection, backgrind and tape/reel capabilities. FlipChip International is integrating the acquired product line into its wafer level packaging and wafer bumping services portfolio.

Commenting on the acquisition, Bob Forcier, President and CEO of FlipChip International, said, “We are very pleased to expand our technology and product investments with the IC Services acquisition. The ability to provide dicing, tape and reel, and in-house backgrinding capability to our customers is part of our five-year roadmap of service expansion.”

Mr. Bruce Bowers, Vice President of FlipChip International and General Manager of the newly acquired product line added, “We are excited about the addition of IC Services’ offerings to our current wafer bumping services. This acquisition marks another milestone in our vision of turn-key die processing, flip chip bumping and wafer level packaging for our customers.”

FlipChip International, LLC is a privately-held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. FlipChip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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